BERGQUIST BOND PLY TBP 850
Known as BERGQUIST BOND-PLY 100
June 2018

PRODUCT DESCRIPTION
Silicone-Free Formulation, High Performance Thermally Conductive Material.

<table>
<thead>
<tr>
<th>Technology</th>
<th>Acrylic</th>
</tr>
</thead>
<tbody>
<tr>
<td>Appearance</td>
<td>White</td>
</tr>
<tr>
<td>Reinforcement Carrier</td>
<td>PEN Film</td>
</tr>
<tr>
<td>Total Thickness</td>
<td>0.14 mm</td>
</tr>
<tr>
<td>Application</td>
<td>Thermal management, Thermally conductive adhesive</td>
</tr>
<tr>
<td>Operating Temperature Range</td>
<td>30 to 120°C</td>
</tr>
</tbody>
</table>

FEATURES AND BENEFITS
- Designed to replace mechanical fasteners or screws
- For applications that require electrical isolation
- Double-sided, pressure sensitive adhesive tape

TYPICAL APPLICATIONS
- Mount heat sink onto BGA graphic processor or drive processor
- Mount heat spreader onto power converter PCB or onto motor control PCB

SHELF LIFE
The double-sided, pressure sensitive adhesive used in LOCTITE BERGQUIST BOND PLY® products requires the use of dual liners to protect the surfaces from contaminants.

The recommended shelf life for BERGQUIST BOND PLY TBP 850 is 6 months at a maximum continuous storage temperature of 35°C or 3-months at a maximum continuous storage temperature of 45°C, for maintenance of controlled adhesion to the liner.

The shelf life of the Bond Ply material, without consideration of liner adhesion (which is often not critical for manual assembly processing), is recommended at 12 months from date of manufacture at a maximum continuous storage temperature of 60°C.

TYPICAL PROPERTIES

Physical Properties
- Temperature Coefficient of Resistance, °C 200
- Elongation, 45° to wrap and fill, ASTM D412, % 70
- Tensile Strength, ASTM D412, MPa 6

Adhesion Properties
- Lap Shear Strength, ASTM D1002:
  @ 25°C N/mm² 0.7 (psi) (100)
  After 5 hours @ 100°C N/mm² 1.4 (psi) (200)
  After 2 minutes @ 200°C N/mm² 1.4 (psi) (200)

Static Dead Weight Shear Strength, PSTC#7, °C 150

Electrical Properties
- Dielectric Breakdown Voltage, ASTM D149:
  @ 0.005″ (Vac) 3,000
  @ 0.008″ (Vac) 6,000
  @ 0.011″ (Vac) 8,500

Thermal Properties
- Thermal Conductivity, ASTM D5470, W/(m-K) 0.8

Thermal Impedance vs. Pressure
- TO-220 Thermal Performance, °C/W:
  @ 0.005″:
    @ 10 psi 5.17
    @ 25 psi 4.87
    @ 50 psi 4.49
    @ 100 psi 4.18
    @ 200 psi 4.1
  @ 0.008″:
    @ 10 psi 5.4
    @ 25 psi 5.35
    @ 50 psi 5.28
    @ 100 psi 5.22
    @ 200 psi 5.2
  @ 0.011″:
    @ 10 psi 6.59
    @ 25 psi 6.51
    @ 50 psi 6.51
    @ 100 psi 6.5
    @ 200 psi 6.4
Thermal Impedance, ASTM D5470, °C·in²/W (1):

<table>
<thead>
<tr>
<th>Pressure</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>@ 0.005&quot;</td>
<td>0.56</td>
</tr>
<tr>
<td>@ 0.008&quot;</td>
<td>0.82</td>
</tr>
<tr>
<td>@ 0.011&quot;</td>
<td>1.03</td>
</tr>
<tr>
<td>@ 0.015&quot;</td>
<td>1.02</td>
</tr>
<tr>
<td>@ 0.020&quot;</td>
<td>1.01</td>
</tr>
<tr>
<td>@ 0.040&quot;</td>
<td>1.0</td>
</tr>
<tr>
<td>@ 0.080&quot;</td>
<td>0.99</td>
</tr>
</tbody>
</table>

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

GENERAL INFORMATION
For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications
The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

CONFIGURATIONS AVAILABLE
BERGQUIST BOND PLY TBP 850 are supplied in:
- Sheet form
- Roll form
- Die-Cut parts

Conversions
(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/m x 5.71 = lb/in
psi x 145 = N/mm²
MPa = N/mm²
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·m·s x 0.142 = oz·in
mPa·s = cP

Disclaimer
Note:
The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.
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Reference 1